

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	255791	(organic) near50 (inorganic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/03/17 15:54	
2	BRS	L3	2	(organic) near50 (inorganic) near50 (moisture) near50 (hermetic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/03/17 15:55	
3	BRS	L4	37	(organic) near50 (inorganic) near50 (hermetic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/03/17 16:06	
4	BRS	L2	1171	(organic) near50 (inorganic) near50 (moisture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/03/17 16:04	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	5083	(organic) near50 (inorganic) near50 (protect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB-	2004/03/17 16:07	
6	BRS	L6	62	(organic) near50 (inorganic) near50 (protect\$3) near40 (chip or die or integrated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB-	2004/03/17 16:08	
7	BRS	L7	86	(organic) near50 (inorganic) near50 (protect\$3) near40 (chip or die or circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB-	2004/03/17 16:17	
8	BRS	L9	1795	(organic) near50 (inorganic or in-organic) near40 (chip or die or circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB-	2004/03/17 16:18	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	L10	3	(organic) near50 (inorganic) near40 (chip or die or circuit) near30 (hermetic)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM- TDB	2004/03/17 16:18	
10	BRS	L8	1794	(organic) near50 (inorganic) near40 (chip or die or circuit)	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM- TDB	2004/03/17 16:20	

	U	1	Document ID	Title	Current OR	Pages	Issue Date
1	<input type="checkbox"/>	<input type="checkbox"/>	US 4636254 A	Silver-glass paste for attachment of silicon die to ceramic substrate	106/1.14	5	19870113
2	<input type="checkbox"/>	<input type="checkbox"/>	US 5123164 A	Hermetic organic-inorganic interconnection substrate for hybrid circuit manufacture - has posts from organic layer plated up sufficiently high to enter holes in ceramic layer which are sealed with solder and plated		6	19920623
3	<input type="checkbox"/>	<input type="checkbox"/>	US 5030499 A	Hermetic organic-inorganic substrate for hybrid circuit manufacture - eliminates release of vapours from bonding adhesive by plating up posts sufficiently high as to enter hole but not to penetrate through it		6	19910709